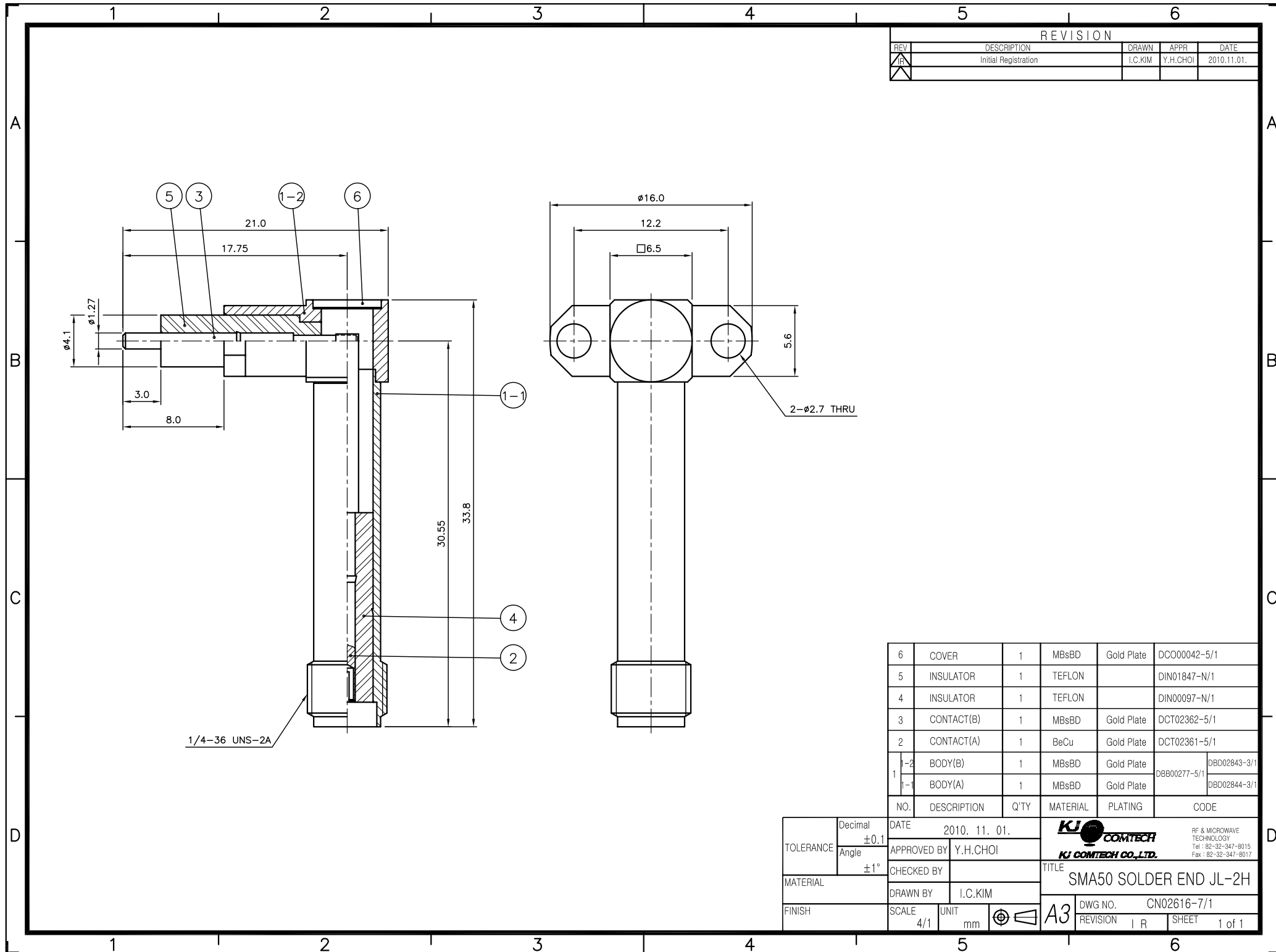




REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
1	Initial Registration	I.C.KIM	Y.H.CHOI	2010.11.01.

6	COVER	1	MBsBD	Gold Plate	DCO00042-5/1
5	INSULATOR	1	TEFLON		DIN01847-N/1
4	INSULATOR	1	TEFLON		DIN00097-N/1
3	CONTACT(B)	1	MBsBD	Gold Plate	DCT02362-5/1
2	CONTACT(A)	1	BeCu	Gold Plate	DCT02361-5/1
1-2	BODY(B)	1	MBsBD	Gold Plate	DBD02843-3/1
1-1	BODY(A)	1	MBsBD	Gold Plate	DBD02844-3/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ± 0.1 Angle $\pm 1^\circ$	DATE 2010. 11. 01.	 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
MATERIAL		APPROVED BY Y.H.CHOI	
FINISH		CHECKED BY	
		DRAWN BY I.C.KIM	
SCALE 4/1	UNIT mm	TITLE SMA50 SOLDER END JL-2H	
		DWG NO. CN02616-7/1	
		REVISION I R	
		SHEET 1 of 1	